

APPLICATION NOTE

Entegris Waffle Trays

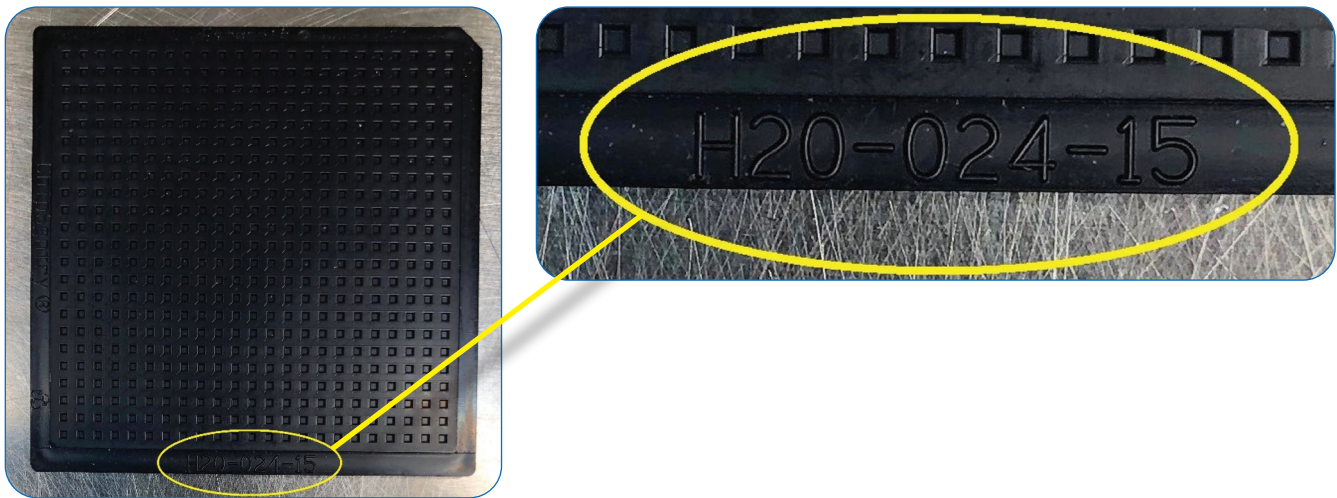
Finding Dimensions and Other Specifications

Introduction

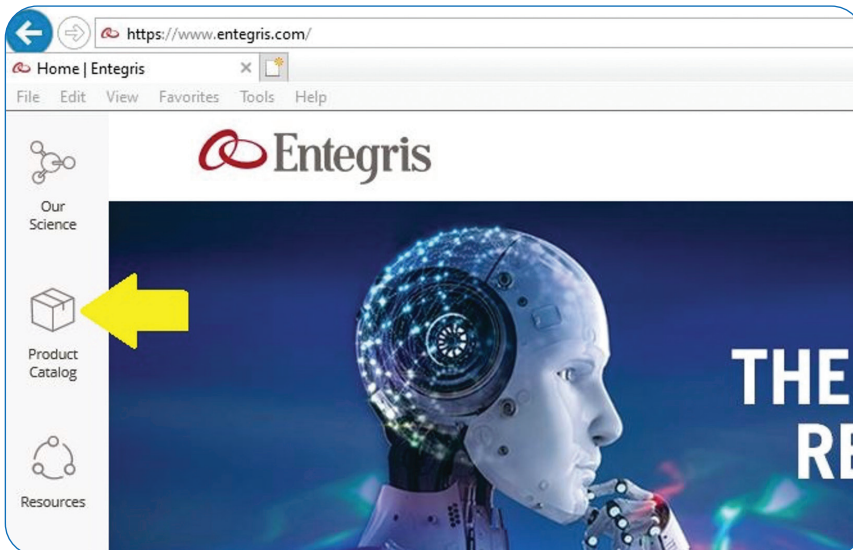
Entegris is a leading global supplier of waffle trays used in the packaging of solder preforms—typically AuSn preforms—as well as other materials and devices, such as semiconductor die.

All the information for specific Entegris waffle trays is generally readily and publicly available on the Entegris website, www.entegris.com

The Entegris part number is embossed on the waffle tray. This is the part number that you will need to research the waffle tray.



Once you have located the Entegris part number, go to the website (www.entegris.com) and click on Product Catalog.



From One Engineer To Another®

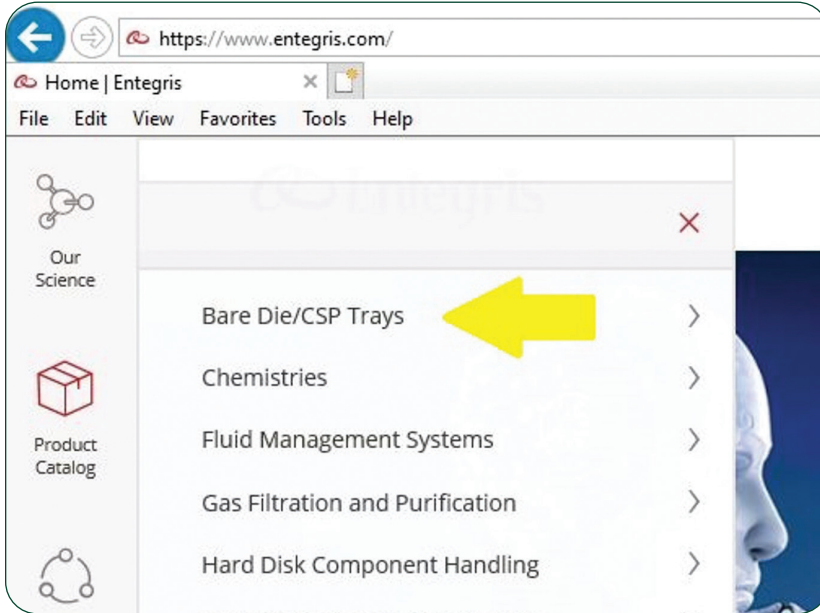


APPLICATION NOTE

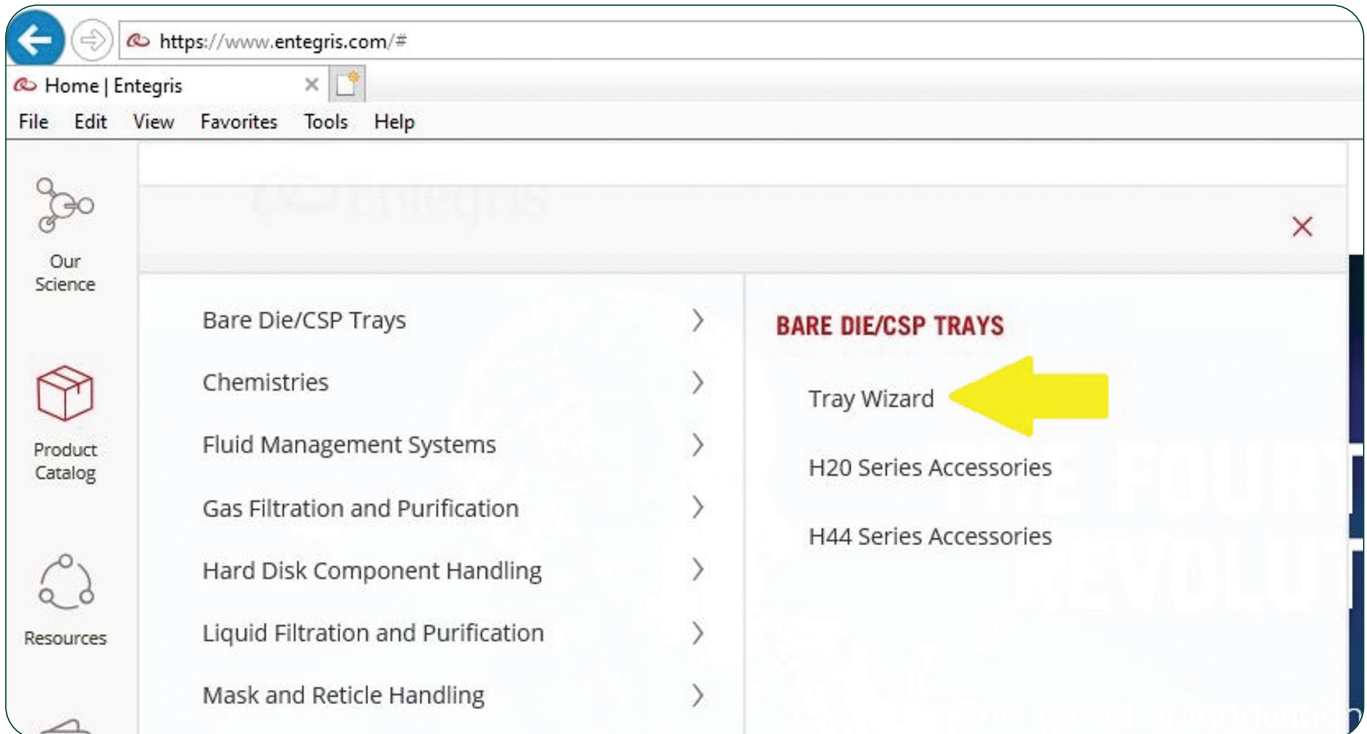
Entegris Waffle Trays

Finding Dimensions and Other Specifications

Click on Bare Die/CSP Trays.



Click on Tray Wizard.



Contact our engineers: askus@indium.com

Learn more: www.indium.com



APPLICATION NOTE

Entegris Waffle Trays

Finding Dimensions and Other Specifications

Scroll down to Part Number Search.

Tray Wizard

Specify search attributes in the available fields and click the 'Search' button.

Search By

Maximum Component Size Nominal Pocket Size

SIZE (in. or mm)

X: 0.000 length

Y: 0.000 width

Z: 0.000 depth

Unit of measure

Inch (ex. 0.205) Millimeter (ex. 1.20)

Tray Series

2" x 2" (H20) 4" x 4" (H44)

Setup Fees

Search active trays only (setup fees may apply based on quantity)

Standard, active trays only (no setup fees)

SEARCH

Part Number Search

Enter the Entegris part number and click on Search.

Part Number Search

Enter a complete or partial part number to search for:

SEARCH

Part Number Search

Enter a complete or partial part number to search for:

H20-024-15 SEARCH

APPLICATION NOTE



Entegris Waffle Trays

Finding Dimensions and Other Specifications

Sometimes, more than one option will be found. This is because Entegris may have more than one option for the waffle tray material, even though the dimensions of the tray will be identical. The suffix of the part number indicates the waffle tray material. However, the suffix is not always embossed on the waffle tray.

Search: H20-024-15

Results 1-2 of 2 matching record(s).

Part Number	Description
H20-024-15-62C02	 H20 Series Bare Die/CSP Tray STAT-PRO® 150 (Black Conductive Polypropylene) Pocket Dimensions: 0.024" x 0.024" x 0.015" Capacity: 23x23 (529)
H20-024-15-66C02	 H20 Series Bare Die/CSP Tray ChipSentry® (Black Conductive Polycarbonate) Pocket Dimensions: 0.024" x 0.024" x 0.015" Capacity: 23x23 (529)

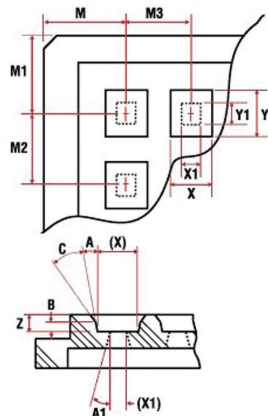
The material of the waffle tray is also embossed on the waffle tray, just like the part number is. In this case, it is ChipSentry®, which corresponds to the part number with the 66C02 suffix. Click on the correct part number.

This will take you to the page on the website that shows the dimensions of the waffle tray.



H20-024-15-66C02 Bare Die / CSP Tray Detail

Dimensions



Note: Image displayed is not an exact representation of the actual product. Part tolerances may differ from the information displayed above. Please contact Customer Service for a complete technical drawing.

Pocket Locations

- M = 0.164" ±0.003"
- M1 = 0.164" ±0.003"
- M2 = 0.076" ±0.002"
- M3 = 0.076" ±0.002"
- Array = 23x23 (529)

Pocket Details

- X = 0.024 pocket size
- Y = 0.024 pocket size
- Z = 0.015 pocket depth
- Contact Technical Customer Service for pocket tolerances
- A = 5° ±1/2° pocket draft angle
- No Cross Slots

Overall Tray Size

- Size = 2.000" ±0.004"
- Height = 0.156" +0.002" -0.003"
- Flatness = 0.004"
- Note = EDM FINISH ON BACK SIDE OF TRAY

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.



Contact our engineers: askus@indium.com
 Learn more: www.indium.com

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900



©2023 Indium Corporation